Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
HP ProCurve Wireless Access Point 520wl (J8133A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Hexnut driver	5mm
Philips Screw Driver	#2
Flat head screw driver	Small

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove base metal plate if attached by sliding it as shown in the fig. #1
2. Disconnect and remove power adapter if present as shown in fig. #2.
3. Remove plastic cover by pulling it away from the metal chassis as shown in fig. #3
4. Remove the 4 screws from the metal chassis by using Philips screw driver #2 shown in fig. #4
5. Remove the 4 hex nut screws holding the PCB by using hex nut driver, shown in fig. #5
6. Remove PCB from the chassis, fig. #6
7. Pry open the power adapter from the side with a flat-head screw driver to remove PCA.
8.
9.
10.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).


Fig.1 Separate metal base by sliding from unit

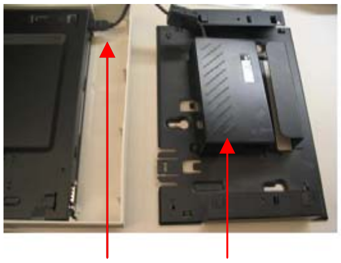
Fig. 2 Disconnect PA and pull out from case


Fig. 3 Pull the unit from plastic case

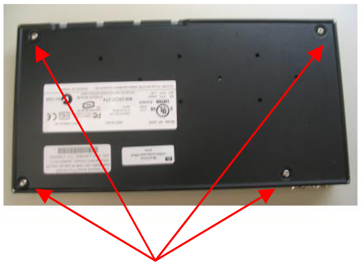
Fig. 4 Remove 4 screws

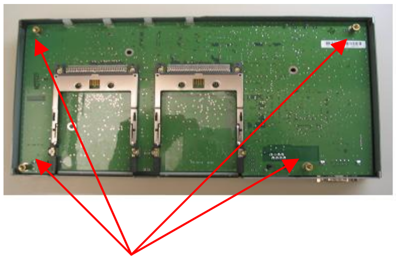
Fig. 5 Remove hex nuts


Fig. 6 Remove PCA.